

Dkt. No.: OP-092000390

AMENDMENTS TO THE CLAIMS:

1. (Currently amended) A protection structure for a thermal conducting medium of a heat dissipation device, comprising:

a bottom surface, being substantially flat to cover the thermal conducting medium;

a side wall extending along and projecting from a periphery of the bottom surface to form a space for receiving the thermal conducting medium and a portion of the heat dissipation device; and

a dented support structure formed in and protruding from the bottom surface to contact on the heat dissipation device so as to avoid a direct contact between the thermal conducting medium and the bottom surface.

2. (Currently amended) The structure of Claim 1, wherein the dented support structure includes a plurality of dented bumps protruding from the bottom surface.

3. (Currently amended) The structure of Claim 1, wherein the dented support structure includes a pair of dented ridges protruding from and extending across the bottom surface.

4. (Original) The structure of Claim 3, wherein the space formed by the side wall is divided into a central space for receiving the thermal conducting medium and a pair of side spaces.

5. (Currently amended) The structure of Claim 4, wherein the dimension surface area of the central space is larger than the surface area of the thermal conducting medium.

6. (Currently amended) The structure of Claim 1, further comprising a plurality of dented friction fit structure protruding from the side wall.

AMENDMENT

10/779,698

- 2 -

Dkt. No.: OP-092000390

7. (Currently amended) The structure of Claim 6, wherein the friction fit structure includes a plurality of dented ribs.

8. (Original) The structure of Claim 1, wherein the top edge of the side wall further includes a flange.

9. (Original) The structure of Claim 1, wherein the heat dissipation device includes a substrate, a plurality of fins projecting from a first surface of the substrate, and the thermal conducting medium attached to a second surface of the substrate.

10. (Original) The structure of Claim 9, wherein the bottom surface is conformal to the substrate.

11. (Original) The structure of Claim 9, wherein the side wall has a height lower than the height of the fins.

12. (Original) The structure of Claim 9, wherein the side wall is level with the tips of the fins.

13. (Original) The structure of Claim 12, further comprising a lid to seal the heat dissipation device within the protection structure.

14. (Currently amended) The structure of Claim 1, wherein the support structure includes a pair of parallel dented ribs.

AMENDMENT

10/779,698

- 3 -